

## ABSTRACT

5 A microsystem enclosure for hermetically sealing and thereby protecting a microsystem located on a substrate from the potentially damaging effects of exposure to moisture, dust, and other external environmental or operating conditions. The enclosure broadly comprises a single-piece hermetic cover structure and a single solder preform. The preform facilitates sealing the cover to the substrate in high-temperature, single-step process so as to create a hermetic cavity wherein the microsystem resides.

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